Module material specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ's, and ordering information posted on our website before purchasing or using this product.

Optional Features and Notes:
- Add "P" to part number for sealing module with epoxy potting.
- Module can be configured in parallel mode as well.
- Performance graphs include thermal resistance of substrates.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
<th>Value</th>
<th>Notes</th>
</tr>
</thead>
<tbody>
<tr>
<td>Vmax (V)</td>
<td>31.4</td>
<td>34.8</td>
<td></td>
</tr>
<tr>
<td>Imax (A)</td>
<td>3.6</td>
<td>3.6</td>
<td></td>
</tr>
<tr>
<td>Qmax (W)</td>
<td>70.0</td>
<td>76.8</td>
<td></td>
</tr>
<tr>
<td>DTmax (°C)</td>
<td>69</td>
<td>78</td>
<td></td>
</tr>
<tr>
<td>Operation/storage temperature</td>
<td>-40 °C to +80 °C</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Unpotted SP-254-1.0-1.3 (Series) at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.

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Potted SP-254-1.0-1.3 (Series) at a hot-side temperature of 30 °C
Unpotted SP-254-1.0-1.3 (Series) at a hot-side temperature of 50 °C

Note: All specifications subject to change without notice.
Potted SP-254-1.0-1.3 (Series) at a hot-side temperature of 50 °C

Note: All specifications subject to change without notice.
Unpotted SP-254-1.0-1.3 (Series) at a hot-side temperature of 70 °C

Note: All specifications subject to change without notice.
Potted SP-254-1.0-1.3 (Series) at a hot-side temperature of 70 °C

Note: All specifications subject to change without notice.
SP-254-1.0-1.3 (Parallel)
Thermoelectric Module
(Peltier Module)
Specifications

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Material Specifications (27 °C hot side temperature)</th>
<th>Material Specifications (50 °C hot side temperature)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Vmax (V)</td>
<td>15.7</td>
<td>17.4</td>
</tr>
<tr>
<td>Imax (A)</td>
<td>7.2</td>
<td>7.2</td>
</tr>
<tr>
<td>Qmax (W)</td>
<td>70.0</td>
<td>76.8</td>
</tr>
<tr>
<td>DTmax (°C)</td>
<td>69</td>
<td>78</td>
</tr>
<tr>
<td>Operation/storage</td>
<td>-40 °C to +80 °C</td>
<td></td>
</tr>
</tbody>
</table>

Module material specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ's, and ordering information posted on our website before purchasing or using this product.

Optional Features and Notes:
- Add "P" to part number for sealing module with epoxy potting.
- Module can be configured in series mode as well.
- Performance graphs include thermal resistance of substrates.

Width, A (mm) 40 +0.5/-0.2
Width, B (mm) 40 +0.5/-0.2
Height, H (mm) 3.6 ±0.05
Flatness, F (mm) 0.02
Parallelism, P (mm) 0.03
Wire Size, WS (mm²) 0.34
Wire Length, WL (mm) 120

RoHS Compliant
Unpotted SP-254-1.0-1.3 (Parallel) at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.
Potted SP-254-1.0-1.3 (Parallel) at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.
Unpotted SP-254-1.0-1.3 (Parallel) at a hot-side temperature of 50 °C

Note: All specifications subject to change without notice.
Potted SP-254-1.0-1.3 (Parallel) at a hot-side temperature of 50 °C

Note: All specifications subject to change without notice.
Unpotted SP-254-1.0-1.3 (Parallel) at a hot-side temperature of 70 °C
Potted SP-254-1.0-1.3 (Parallel) at a hot-side temperature of 70 °C

Note: All specifications subject to change without notice.